

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Yao, et al.

Serial No. 09/457,929

Filed:

December 8, 1999

For: WAFER CARRIER AND SEMICONDUCTOR APPARATUS FOR PROCESSING A SEMICONDUCTOR SUBSTRATE San Francisco, CA 94111

Examiner: Jeffrie R. Lund

Date: March 4, 2002

Group Art Unit: 1763

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CERTIFICATE OF MAILING (37 CFR 1.8(A))

I hereby certify that this paper (along with any referred to as being attached or enclosed) is being deposited with the United States Postal Service on the date shown below with sufficient postage as First Class Mail in an envelope addressed to: Box Missing Parts, Commissioner of Patents and Trademarks, Washington, D.C. 20231 on *March 4, 2002*.

Signed: Kari Bateman

TRANSMITTAL LETTER

Assistant Commissioner for Patents Washington, DC 20231

Sir:

Please find enclosed the following documents relating to the subject patent application:

- [X] Amendment in response to Office Action dated September 4, 2001;
- [X] Petition for Extension of Time (Three Months);
- [X] Check No. 008067in the amount of \$920.00 (\$920 for Petition for Three Month Extension of Time for large entity);
- [X] Please charge any additional fees or credit any overpayment to Deposit Account No. 06-1300 (Order No. <u>A-64873-1/AJT/MSS</u>). A copy of this sheet is enclosed for such purpose.

[X] Return Postcard.

Respectfully submitted,

By: 7 / Aun Mana

Maria \$. Swiatek, Reg. No. 37,244

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AMENDMENT

Assistant Commissioner for Patents Washington, D.C. 20231

Sir:

The following is in response to the Office Action dated September 4, 2001. Please amend the referenced application as follows:

IN THE SPECIFICATION

Please replace the paragraph beginning at page 7, line 3, with the following rewritten

To maintain the desirable line or point contact with the peripheral edge of the wafer and to provide secure support of the wafer, the thermal expansion of the wafer carrier is considered. Preferably, little thermal expansion occurs during the process so that the desired angle of the incline is preserved. Specifically, the wafer carrier is comprised of a material having a coefficient of thermal expansion in the range of 2.6×10^{-6} C to 5×10^{-6} C, with the lower values preferred. Materials with

A-64873-1/AJT/MSS 1037372

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